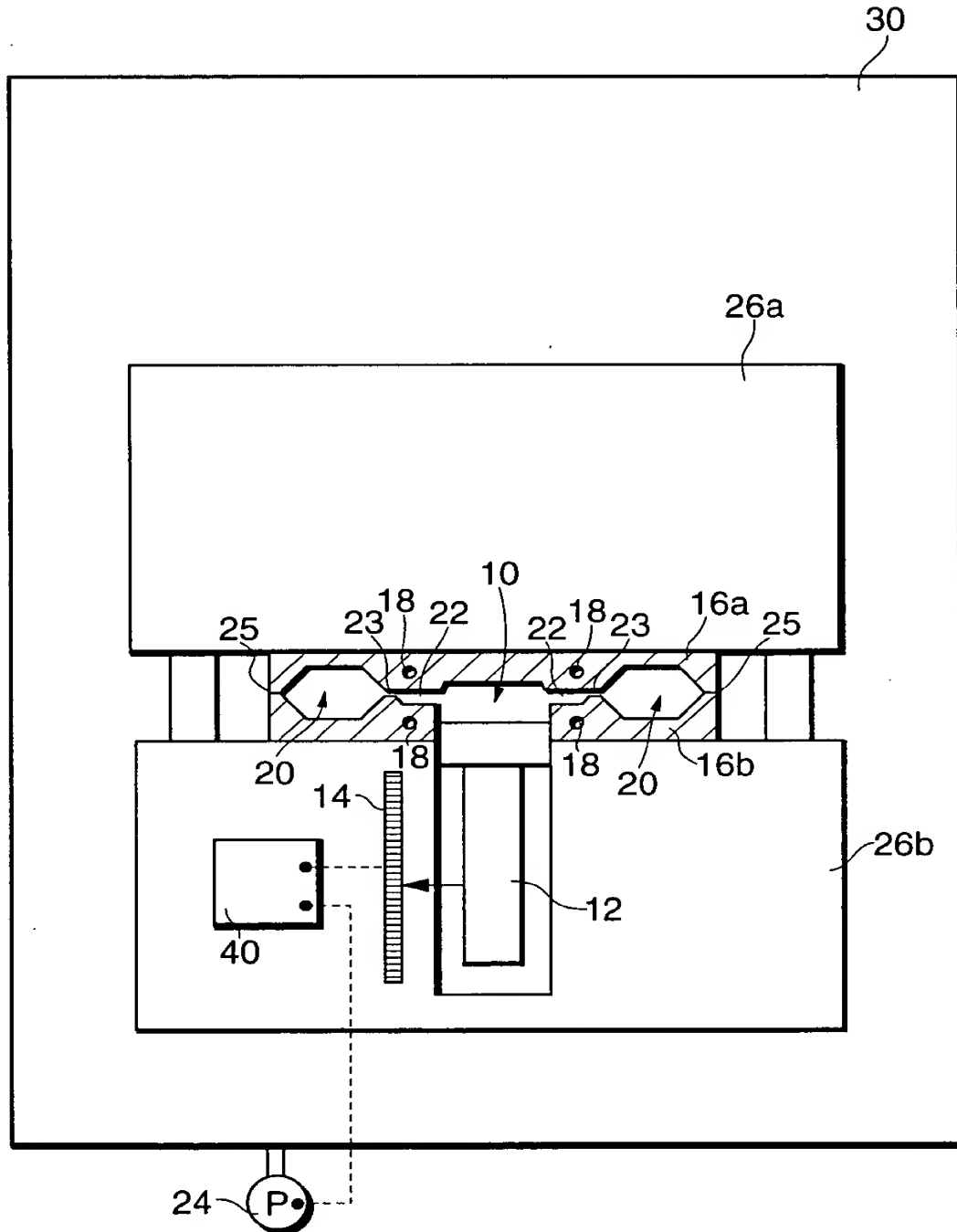


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**Fig. 1**



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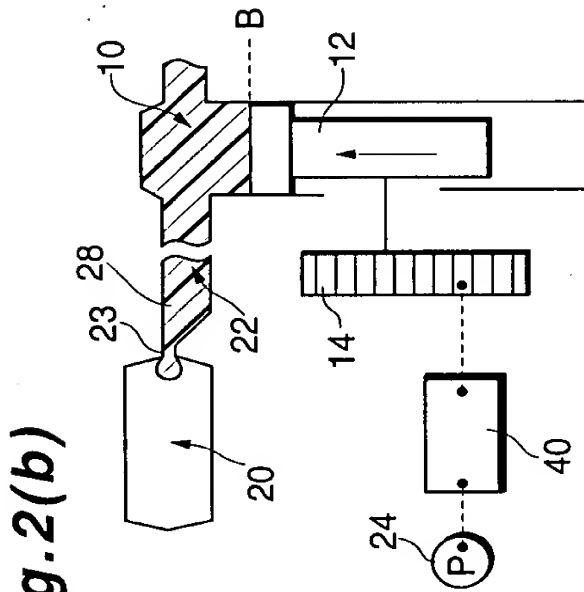


Fig. 2(a)

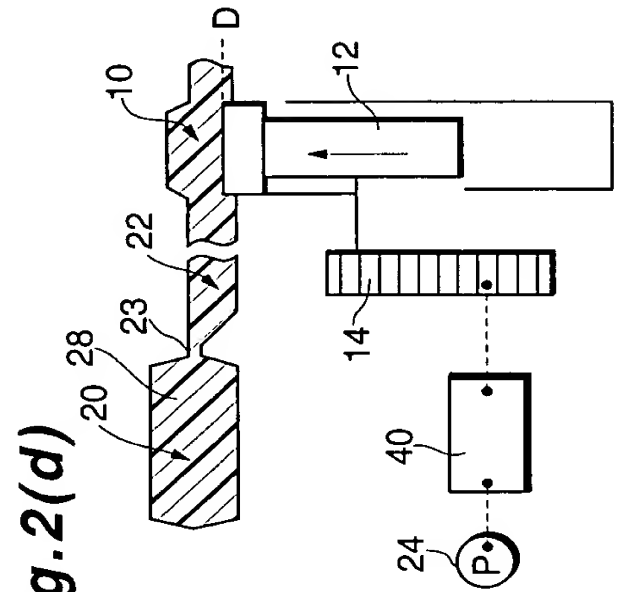


Fig. 2(b)

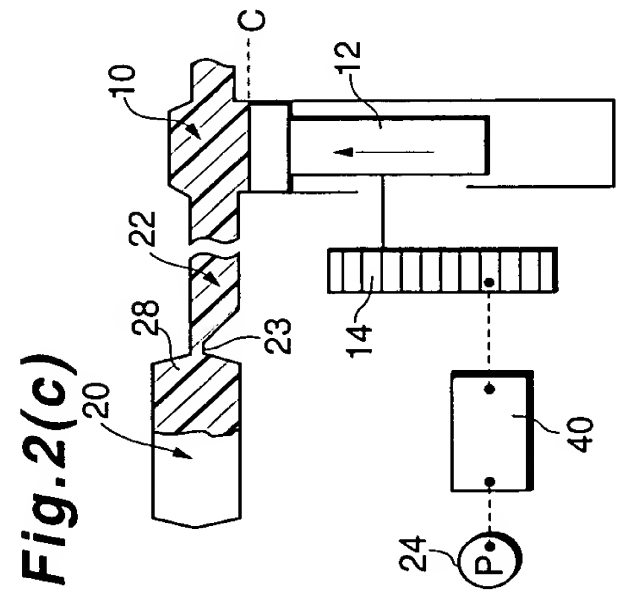


Fig. 2(c)

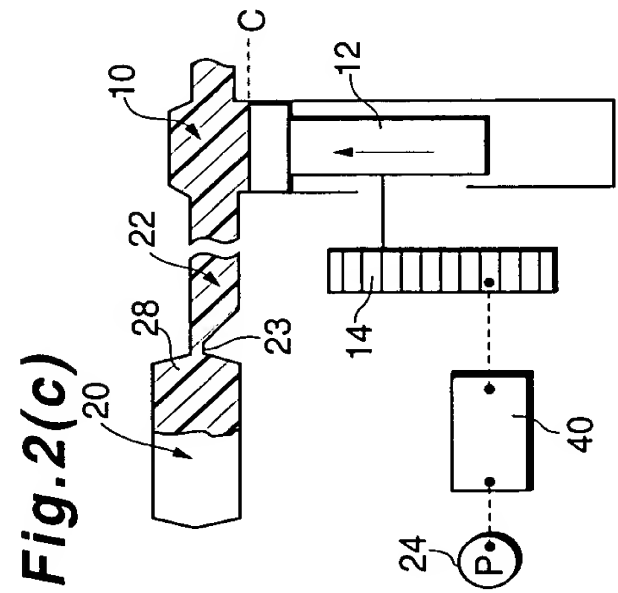
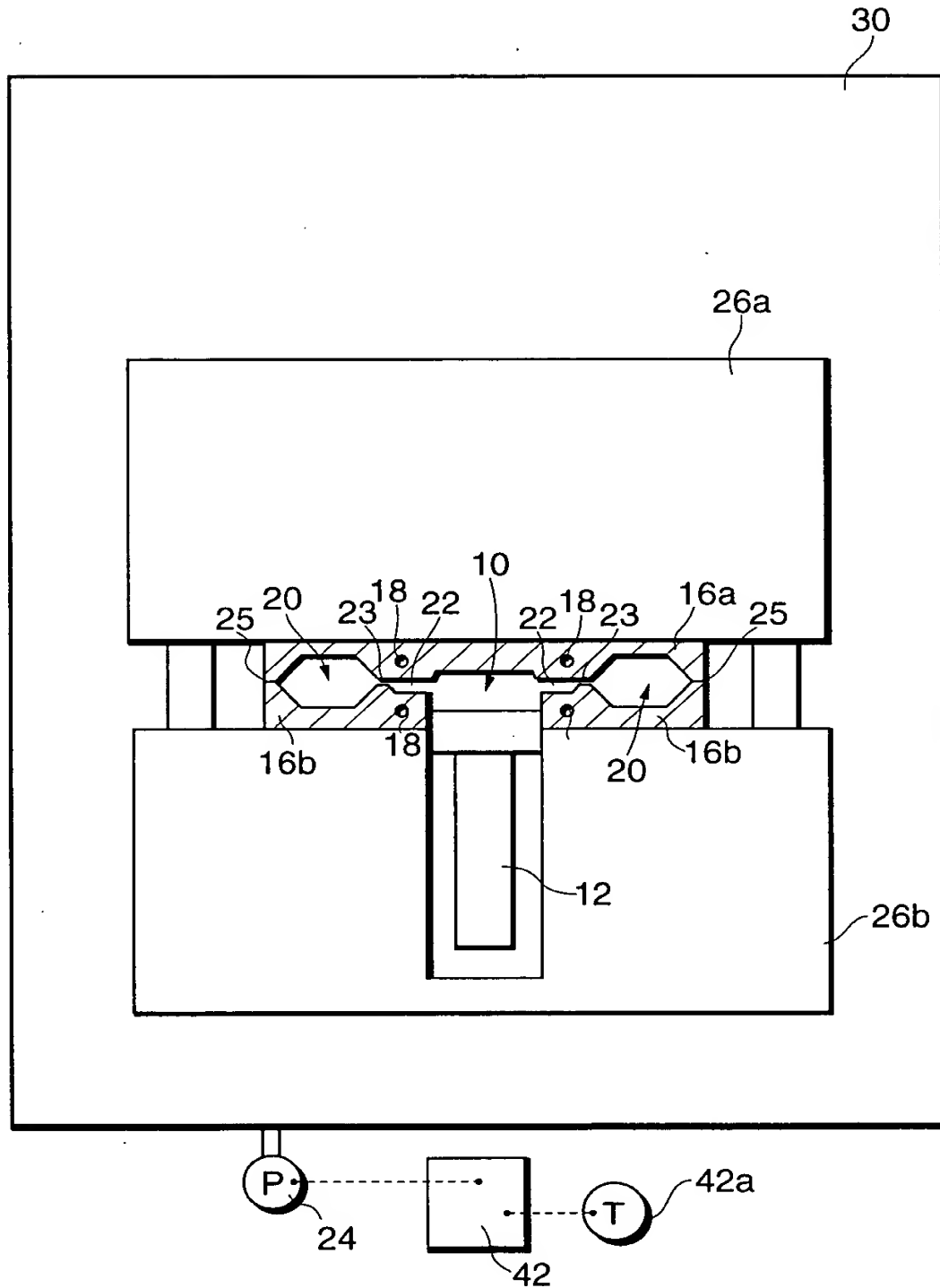
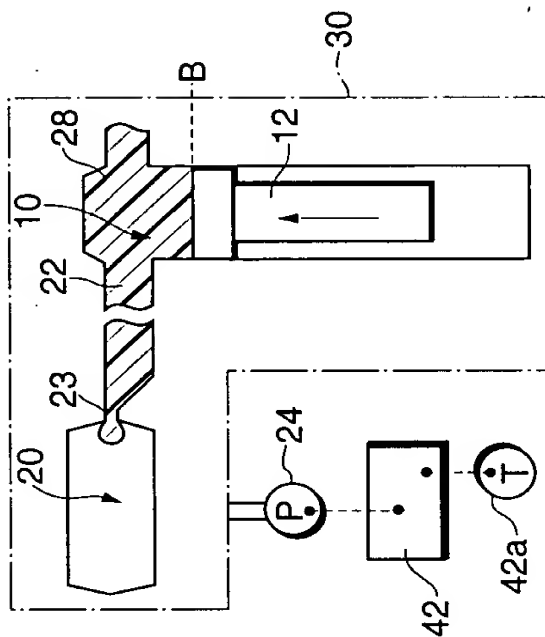


Fig. 2(d)

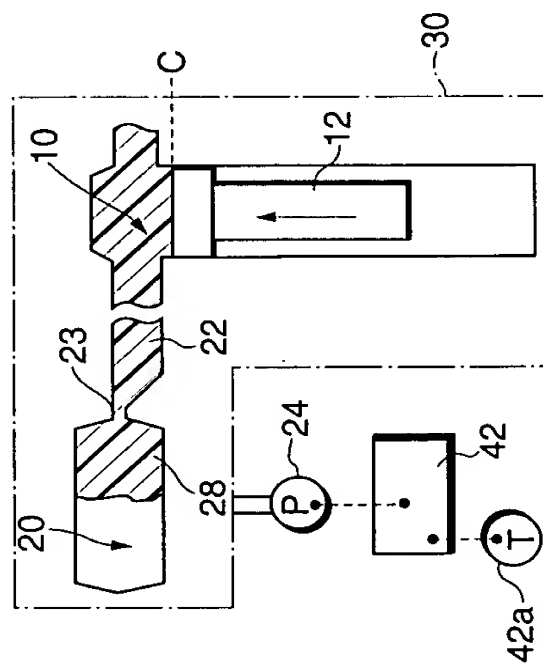
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**Fig.3**

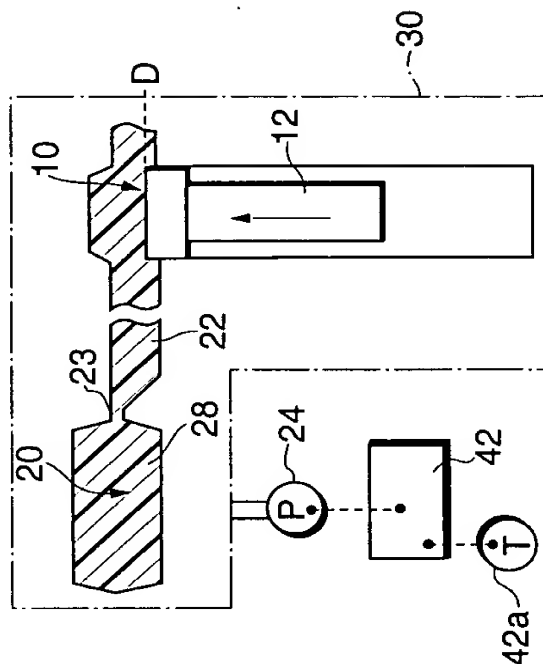




**Fig. 4(c)**

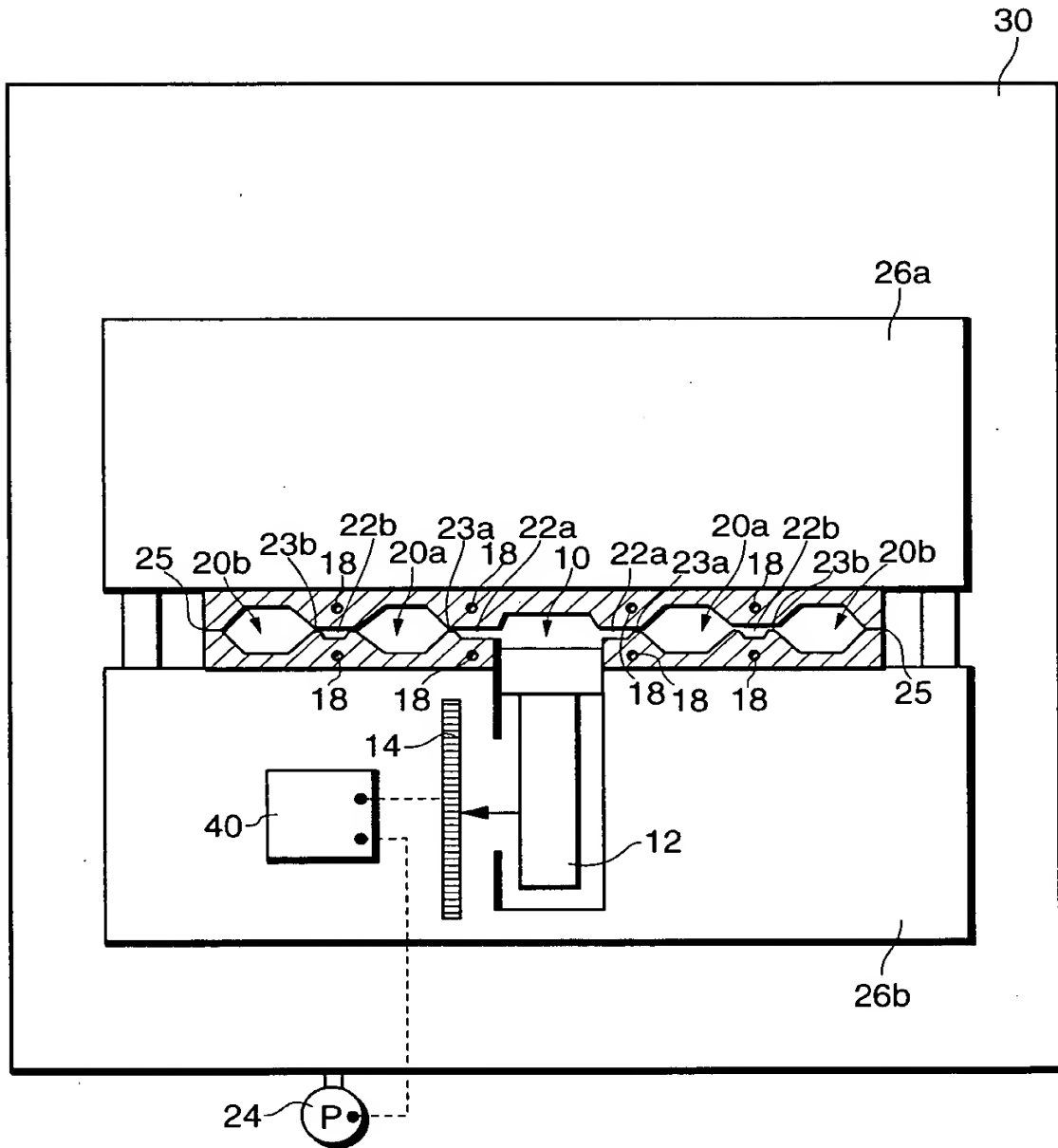


**Fig. 4(d)**

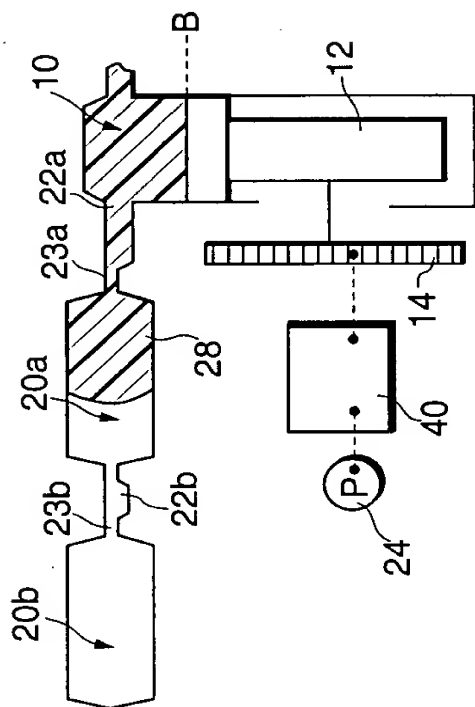


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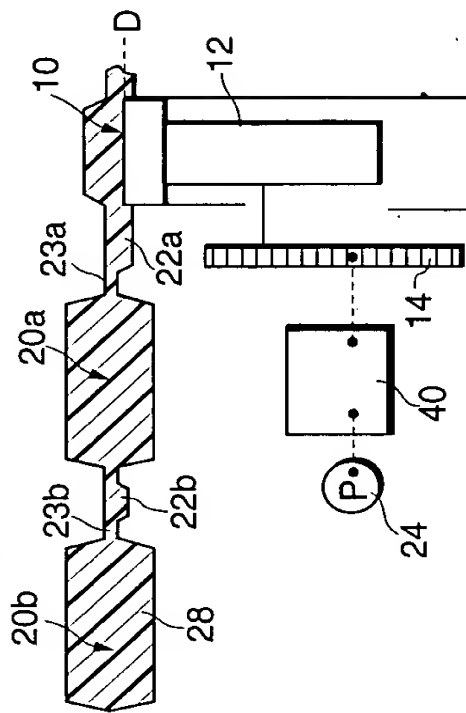
**Fig.5**



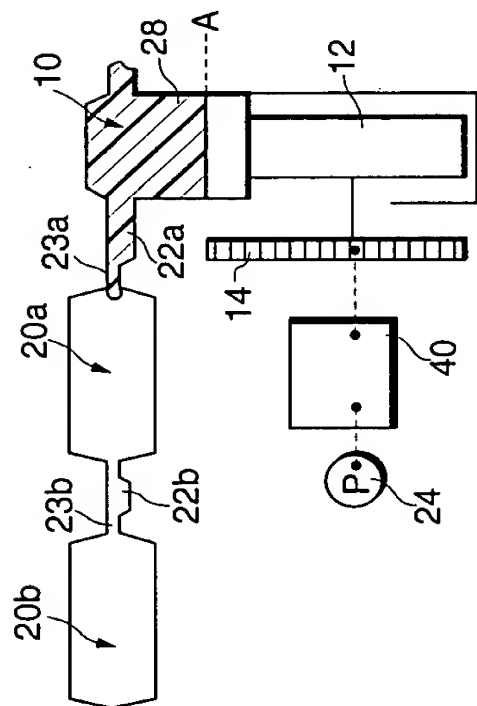
**Fig. 6(b)**



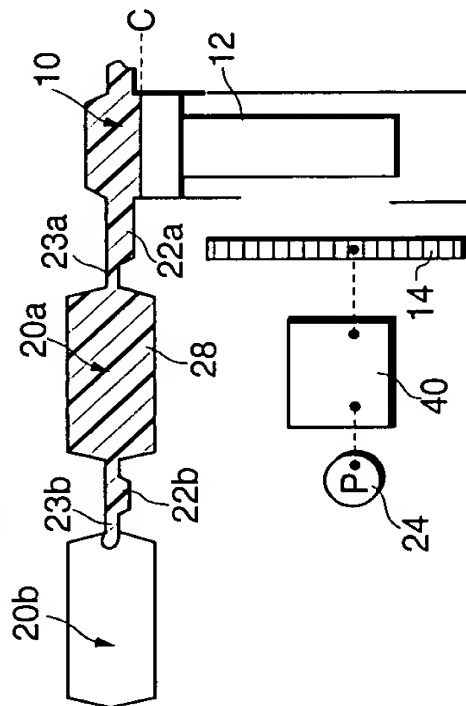
**Fig. 6(d)**



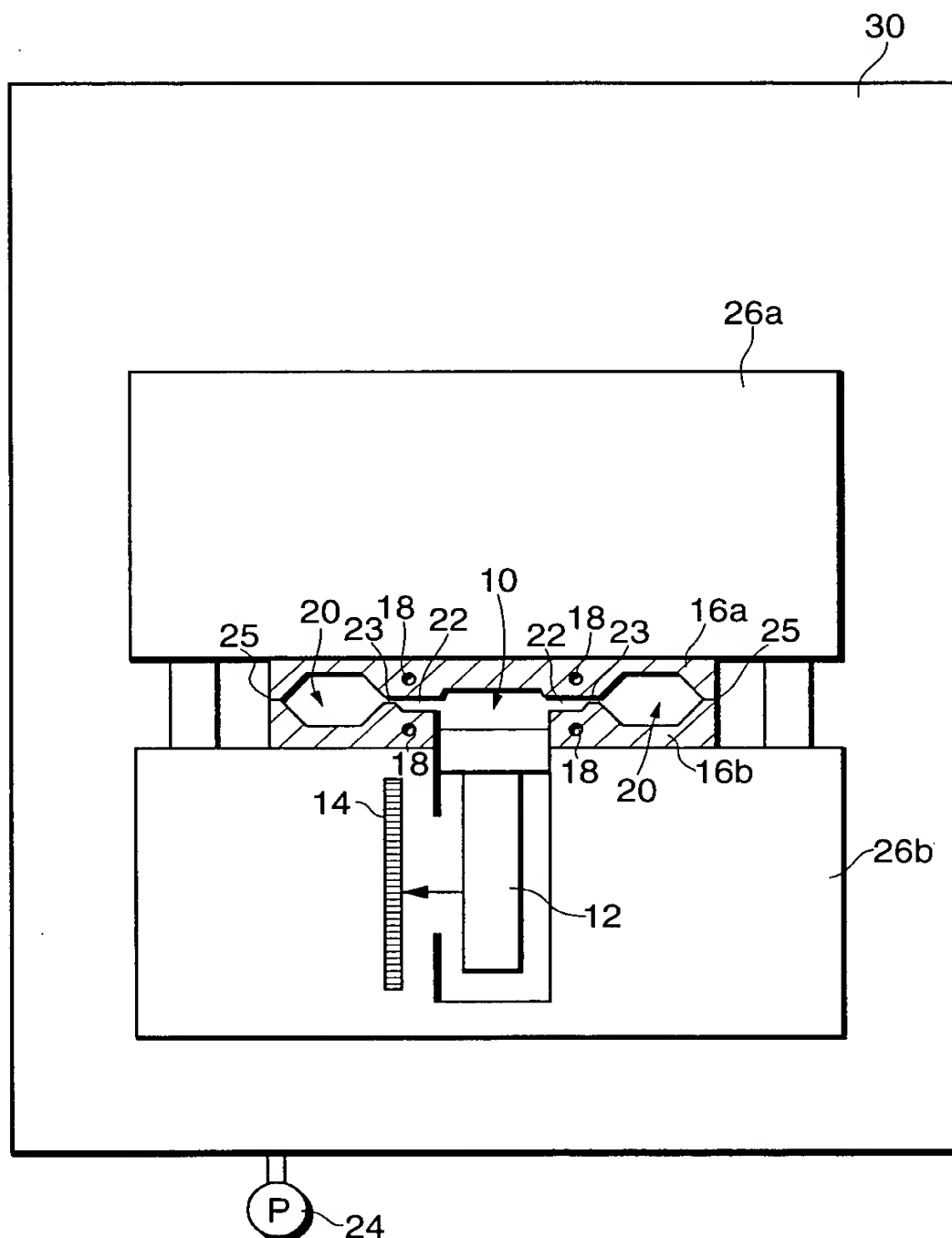
**Fig. 6(a)**



**Fig. 6(c)**



**Fig.7**



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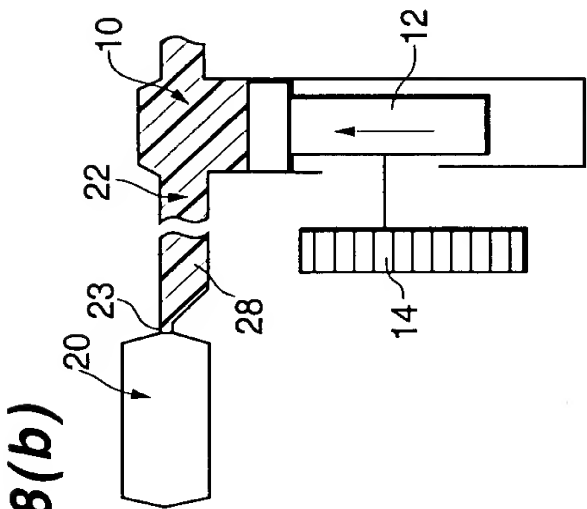


Fig. 8(a)

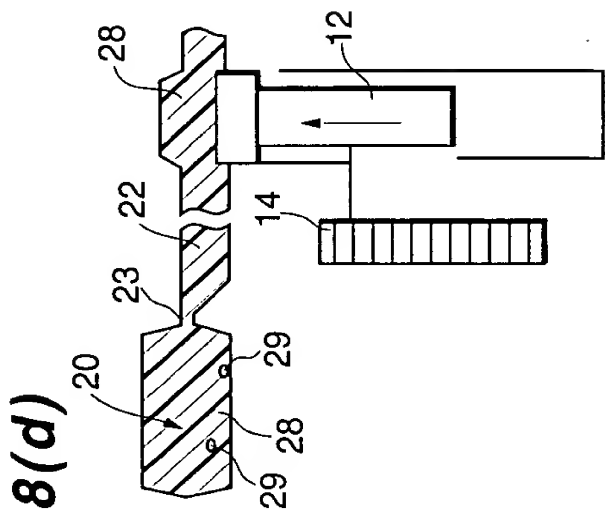


Fig. 8(b)

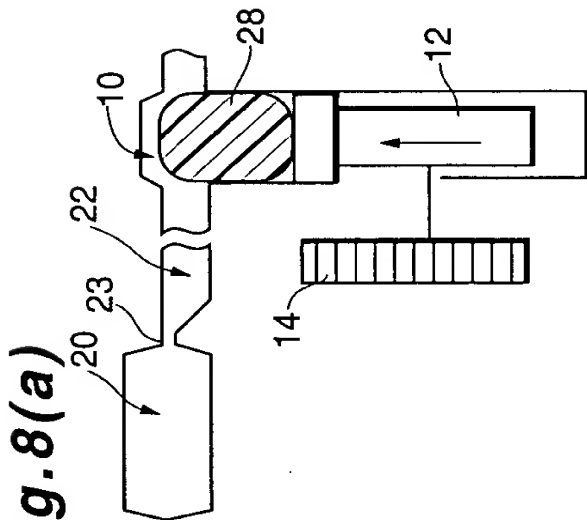


Fig. 8(c)

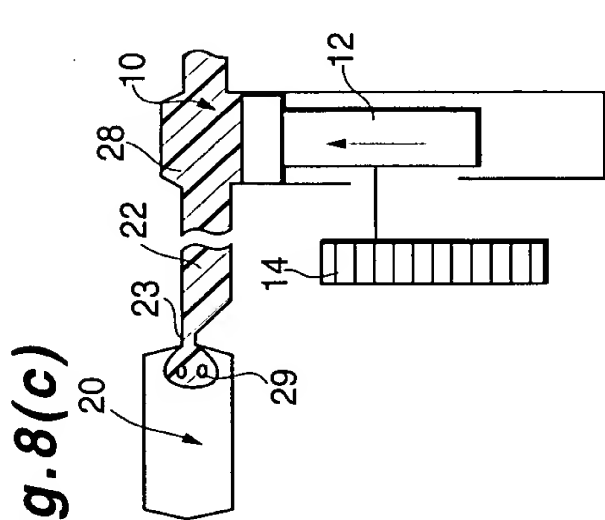


Fig. 8(d)